

WHAT IS CLAIMED IS:

1. A ceramic electronic component comprising
a chip of an electronic component containing inner wiring
and at least one terminal electrode on an outer surface
of the electronic component electrically connected to the
5 inner wiring, wherein

the terminal electrode comprises a first
layer on an outer surface of the electronic component, a
second layer on the outside of the first layer and a
third layer on the outside of the second layer, and
10 wherein the second layer is porous.

2. A ceramic electronic component according
to Claim 1 having two of said terminal electrodes
disposed at different sites on the outer surface of the
electronic component.

3. A ceramic electronic component according
to Claim 2, wherein the second layer comprises baked
conductive particles of a particle size of about 3 to 6
 μm .

4. A ceramic electronic component according
to Claim 3, wherein the first, second and third layers
each comprise baked conductive particles of a particle
size of about 0.5 to 2 μm .

5. A ceramic electronic component according
to Claim 2, wherein the first, second and third layers
each comprise baked conductive particles of a particle
size of about 0.5 to 2 μm .

6. A method for producing a chip of a ceramic electronic component having inner wiring electrically connected to a terminal electrode on the outer surface of the electronic component, comprising the steps of:

5 providing said electronic component having inner wiring;

forming a first conductive paste film containing conductive particles to form a first layer by baking on a portion of the outer surface of the
10 electronic component;

forming at the side of the first conductive paste film exterior to the electronic component, a second conductive paste layer containing conductive particles and an additive which burns out when
15 the layer is baked to form a second layer;

forming a third conductive paste layer containing conductive particles to form a third layer by baking at the side of the second conductive paste film exterior to the first layer; and

20 baking the resulting composite.

7. A method for producing the ceramic electronic component according to Claim 6, further comprising the step of adjusting the content of additive in the second conductive paste film in order to obtain a
5 predetermined void ratio in the porous structure of the second layer after baking.

8. A method for producing the ceramic electronic component according to Claim 7, wherein the second conductive paste film is dried prior to the step for forming the third conductive paste film, and the

5 second conductive paste film is baked simultaneously with the third conductive paste.

9. A method for producing the ceramic electronic component according to Claim 8, wherein the additive comprises gelatin, cellulose or carbon.

10. A method for producing the ceramic electronic component according to Claim 9, wherein the second paste film comprises conductive particles having a particle size of about 3 to 6 μm .

11. A method for producing the ceramic electronic component according to Claim 10, wherein the first, second and third paste films each comprise conductive particles having a particle size of about 0.5 to 2 μm .
5

12. A method for producing the ceramic electronic component according to Claim 7, wherein the additive comprises gelatin, cellulose or carbon.

13. A method for producing the ceramic electronic component according to Claim 12, wherein the second conductive paste film is dried prior to the step for forming the third conductive paste film, and the second conductive paste film is baked simultaneously with the third conductive paste.
5

14. A method for producing the ceramic electronic component according to Claim 13, wherein the second paste film comprises conductive particles having a particle size of about 3 to 6 μm .

15. A method for producing the ceramic electronic component according to Claim 14, wherein the first, second and third paste films each comprise conductive particles having a particle size of about 0.5 to 2 μm .

16. A method for producing the ceramic electronic component according to Claim 6, wherein the second paste film comprises conductive particles having a particle size of about 3 to 6 μm .

17. A method for producing the ceramic electronic component according to Claim 16, wherein the first, second and third paste films each comprise conductive particles having a particle size of about 0.5 to 2 μm .

18. A method for producing the ceramic electronic component according to Claim 6, wherein the first, second and third paste films each comprise conductive particles having a particle size of about 0.5 to 2 μm .

19. A method for producing the ceramic electronic component according to Claim 6, wherein the second conductive paste film is dried prior to the step for forming the third conductive paste film, and the second conductive paste film is baked simultaneously with the third conductive paste.